

## Datasheet

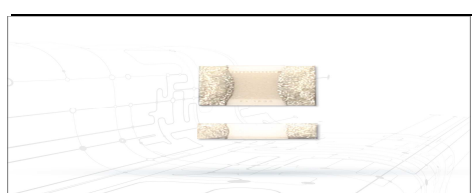
## 08x05SMDPt100B-C

## 181008

### Summary

This platinum-chip temperature sensor is characterized by its small size and can therefore allow a very high packing density. It is preferably used for automated assembly, for example, electrical printed circuit boards in large-scale production.

### Dimensions in mm

	L	B	H	Solder-connection
	2,0 ±0,2	1,3 ± 0,2	0,5 ±0,2	Ca. 0,4

### Technical specifications

Nominal resistance $R_0$ at 0°C	Specification	Tolerance	Order Number	Item Number
100 Ω	DIN EN 60751	F 0,3 (DIN B)	08x05SMDPt100B-C	181008

Temperature range:	-50 ° C to +150 ° C in continuous operation Validity of tolerance F 0.3: -30 ° C to +150 ° C		
Temperature coefficient:	TK = 3850 ppm / K		
SMD size:	comply with the standards CECC 40401-004 / DIN 45921		
Processing:	reflow soldering (soldering temperature / time ≤ 240 ° C / 8 s) Surge wave soldering (soldering temperature / time ≤ 260 ° C / 10 s)		
Solder connections:	tinned wrap-around contact with diffusion barrier		
Conditions of use:	The sensor must not unprotected in humid environments or aggressive nuclear sphere be used.		
Long-term stability:	max. $R_0$ -drift ≤ 0.05 % / year		
Insulation resistance:	> 10 M at room temperature		
Vibration resistance:	DIN EN 60751, Section 4.4.2.		
Self-heating:	0.15 K / mW		
Response:	water current (v = 0.4 m / s):	$\tau_{0,5} = 0.1$ s	$\tau_{0,9} = 0.3$ s
	Air flow (v = 1 m / s):	$\tau_{0,5} = 2.6$ s	$\tau_{0,9} = 7.9$ s
Packaging:	Taped		
<b>Note:</b>	<b>Please refer to our application and installation instructions</b>		
RoHS compliant			

Technische Änderungen behalten wir uns vor. Alle technischen Angaben sind Beschaffenheitsangaben und sichern keine Eigenschaften zu.

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